



原厂直供，技术支持。 联系人：李生 电话：18126115420（微信同号）**ASC100N1700MT4**

1700V N-Channel MOSFET

Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

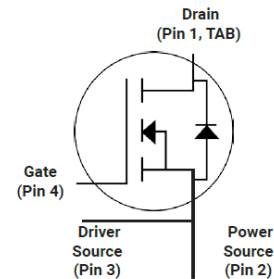
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- 100% avalanche tested
- Maximum junction temperature of 150°C
- ROHS Compliant



Application

- EV Charging
- DC-AC Inverters
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives



Part Number	Marking	Package	Packaging
ASC100N1700MT4	ASC100N1700MT4	TO-247	Tube



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Absolute Maximum Ratings(Tc=25°C)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	1700	V
I _D	Drain Current(continuous)at Tc=25°C	100	A
I _D	Drain Current(continuous)at Tc=100°C	68	A
I _{DM}	Drain Current (pulsed)	200	A
V _{GS}	Gate-Source Voltage	-10/+25	V
P _D	Power Dissipation T _C = 25°C	420	W
T _J , T _{stg}	Junction and Storage Temperature Range	-55 to +150	°C

Electrical Characteristics(T_J = 25°C unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV _{DS}	Drain-source Breakdown Voltage	I _D =250uA, V _{GS} =0V	1700			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =1700V, V _{GS} =0V, T _J =25°C			100	uA
I _{GSS}	Gate-body Leakage Current	V _{DS} =0V ; V _{GS} =-10 to 20V			250	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =20mA	2		4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} =20V, I _D =50A		20	30	mΩ
R _G	Gate Resistance	V _{GS} =0V, f=1MHz		3		Ω

Typical Performance-Dynamic

C _{iss}	Input Capacitance	V _{DS} =800V, f=1000KHZ, V _{GS} =0V	4850		pF
C _{oss}	Output Capacitance		128		pF
C _{rss}	Reverse Transfer Capacitance		18		pF
Q _g	Total Gate Charge	V _{DS} =800V, I _D =50A, V _{GS} =-4~20V	160		nC
Q _{gs}	Gate-source Charge		56		nC
Q _{gd}	Gate-Drain Charge		46		nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =800V, I _D =50A, V _{GS} =-4V~20V, R _G =0Ω,	146		ns
t _r	Rise Time		28		ns
t _{d(off)}	Turn-off Delay Time		77		ns
t _f	Fall Time		22		ns



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Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =30A, T _J =25°C	3		6	V
		V _{GS} =0V, I _F =30A, T _J =150°C	3		6	V
t _{rr}	Reverse Recovery Time	V _{GS} =0 V, I _F =30 A, V _R =800 V, di/dt= 100 A/μs		92		ns
Q _{rr}	Reverse Recovery Charge			780		nC
I _{rrm}	Peak Reverse Recovery Current			19		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.3	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Case	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=150°C



● **Electrical characteristic curves**

Fig.1 Typical Output Characteristics(I)

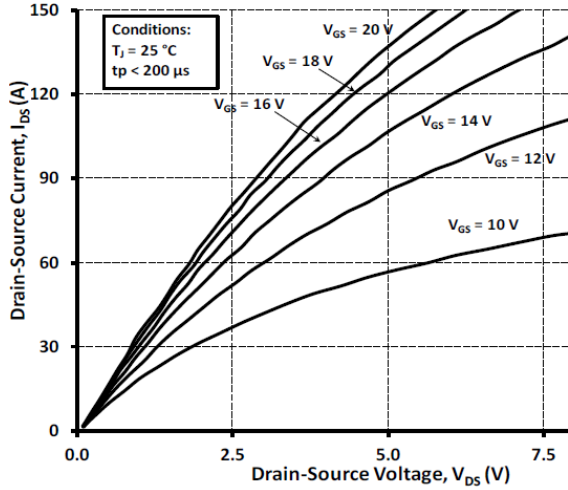


Fig.2 Typical Output Characteristics(II)

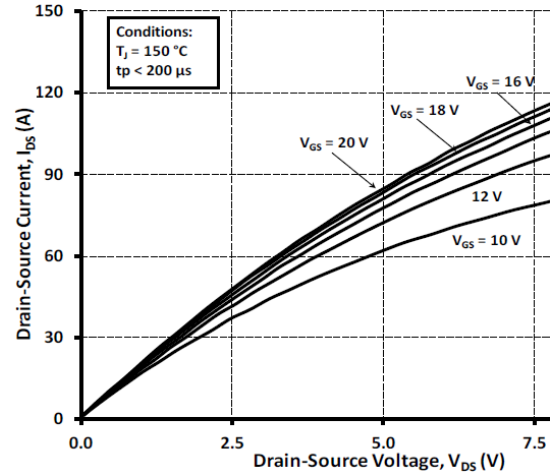


Figure 3. Normalized On-Resistance vs. T_J

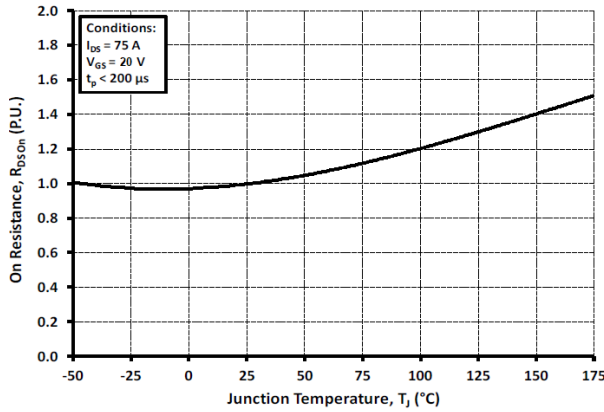


Figure 4. On-Resistance vs. Drain Current

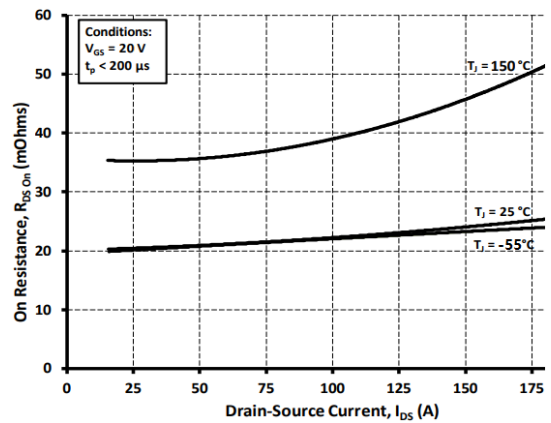


Figure 5. Transfer Characteristic for Various T_J

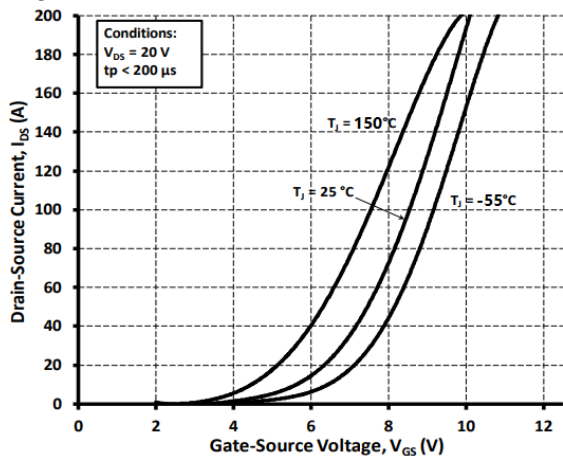


Figure 6. Body Diode Characteristic

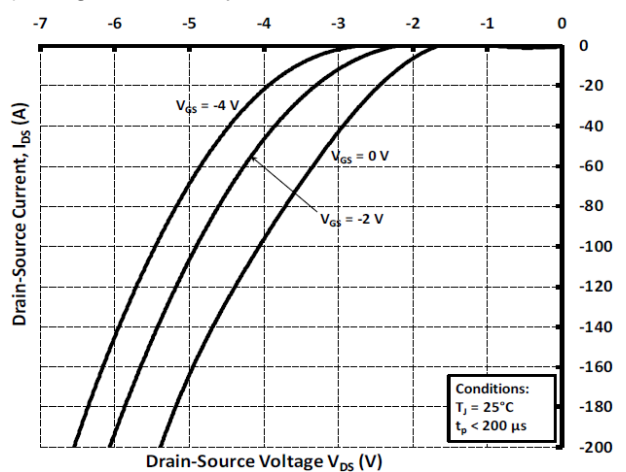




Figure 7. Threshold Voltage vs. T_j

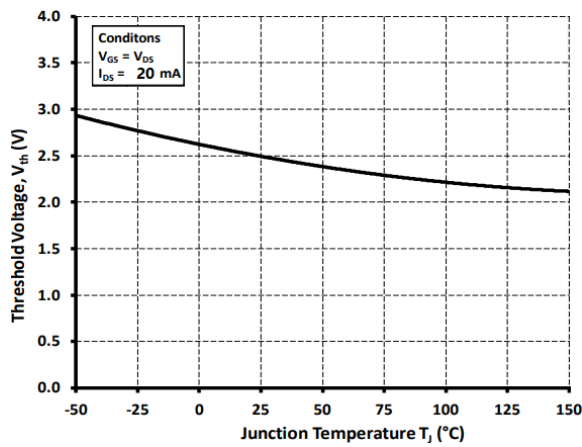


Figure 8. Gate Charge Characteristics

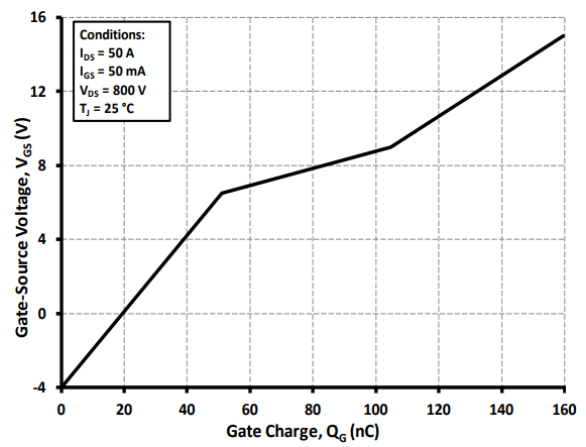


Figure 9. Output Capacitor Stored Energy

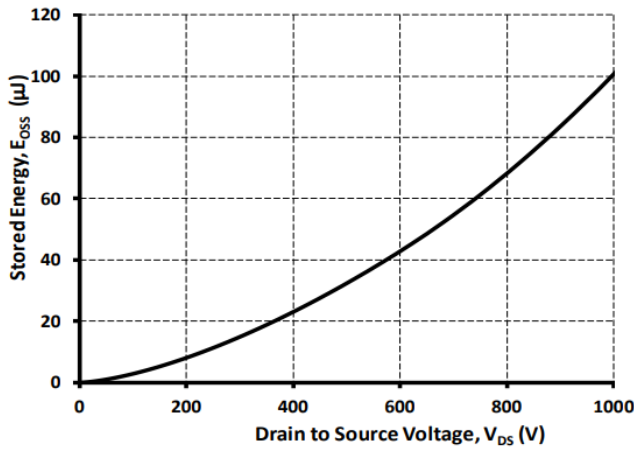


Figure 10. Capacitances vs. V_{DS}

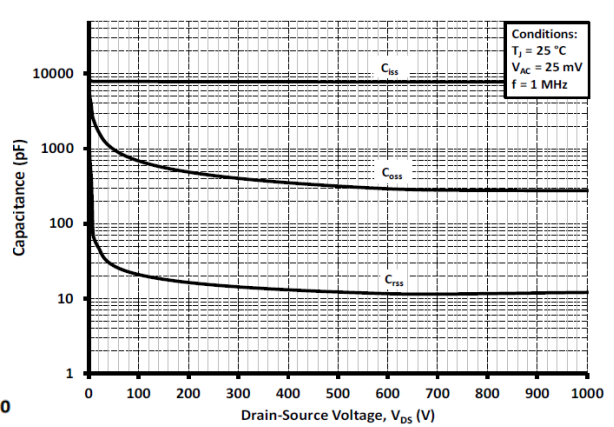


Figure 11. Continuous Drain Current vs. T_c

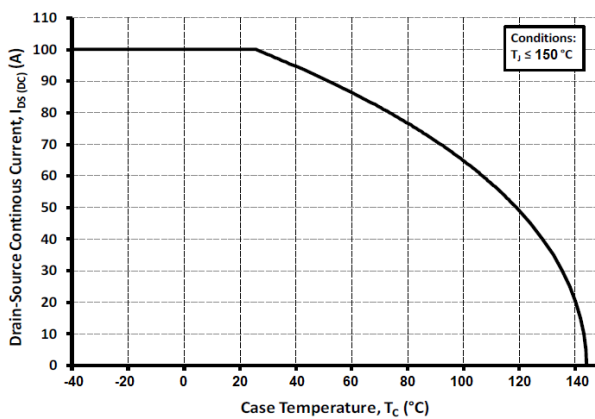


Figure 12. Maximum Power vs. T_c

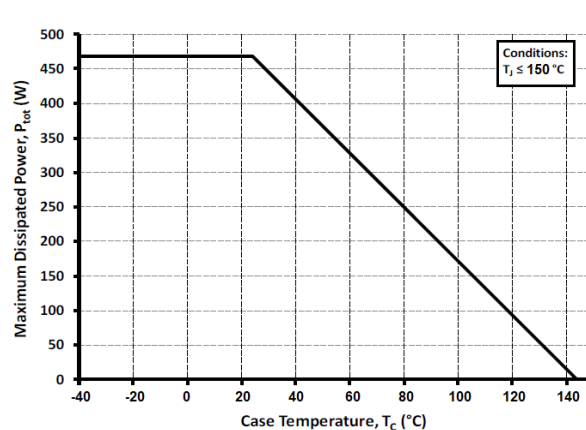




Figure 13. Transient Thermal Impedance

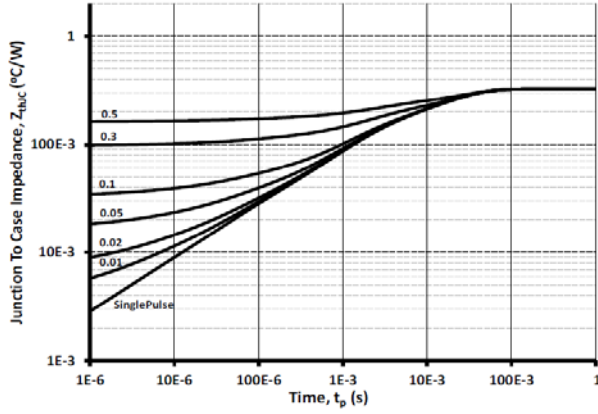


Figure 14. Safe Operating Area

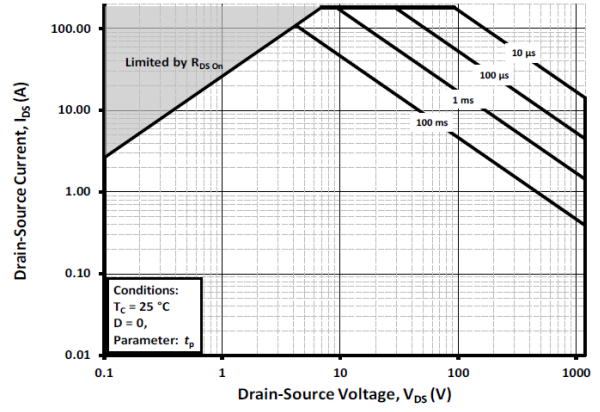


Figure 15. Switching Energy vs. RG(ext)

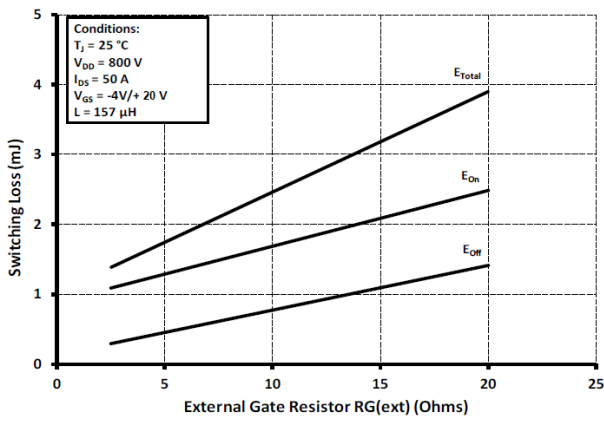
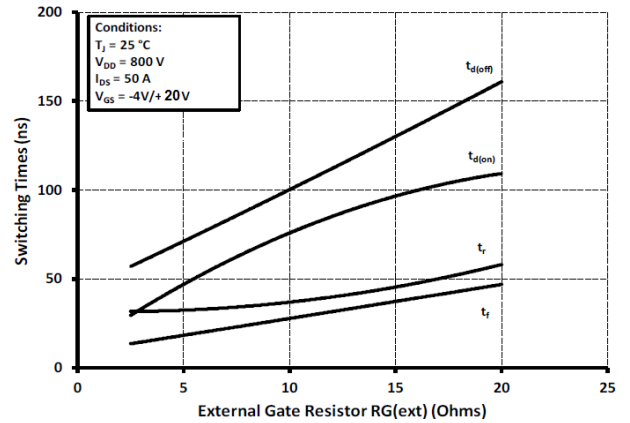


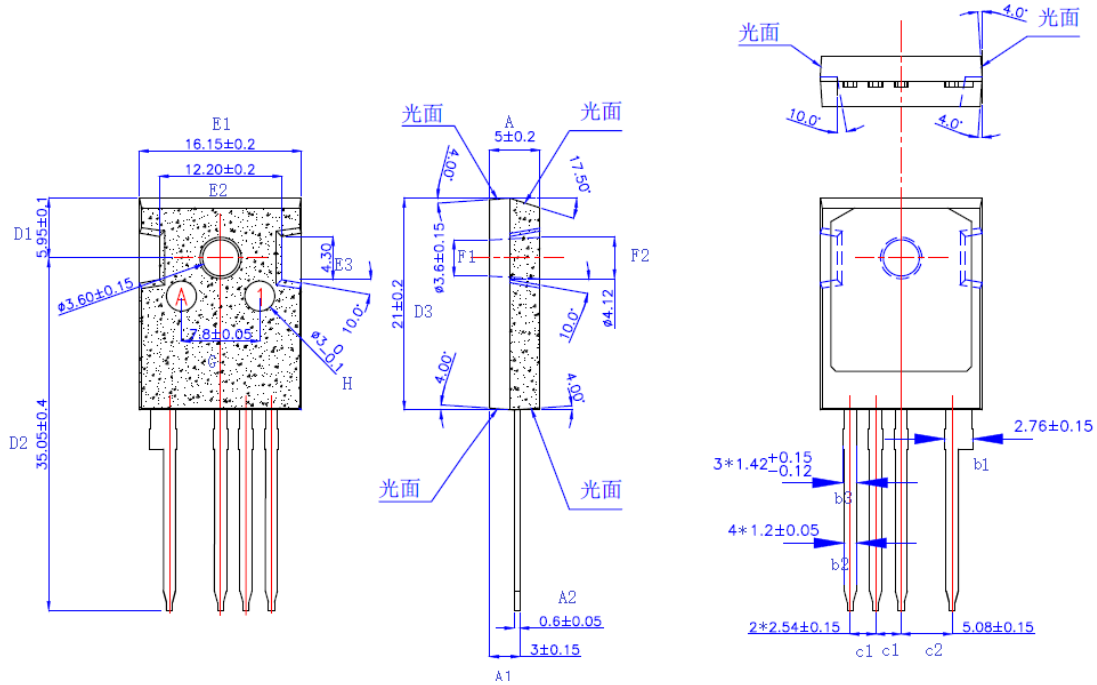
Figure 16. Switching Times vs. RG(ext)





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Package Drawing:



Dimensions (UNIT: mm)

SYM	MILLIMETERS		SYM	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.98	5.02	D2	34.65	35.45
A1	2.85	3.15	D3	20.80	21.20
A2	0.55	0.65	E1	15.95	16.35
b1	2.61	2.91	E2	12.00	12.40
b2	1.15	1.25	F1	3.45	3.75
b3	1.30	1.57	F2	4.12	4.12
c1	2.39	2.69	G	7.75	7.85
c2	4.93	5.23	H	2.90	3.10
D1	5.85	6.05			